



# Update on Silicon Pixel Readout for a TPC at NIKHEF

TILC09 - Tsukuba

18 April 2009

Jan Timmermans

NIKHEF

# Full post-processing of a TimePix

· Timepix chip + SiProt + Ingrid:

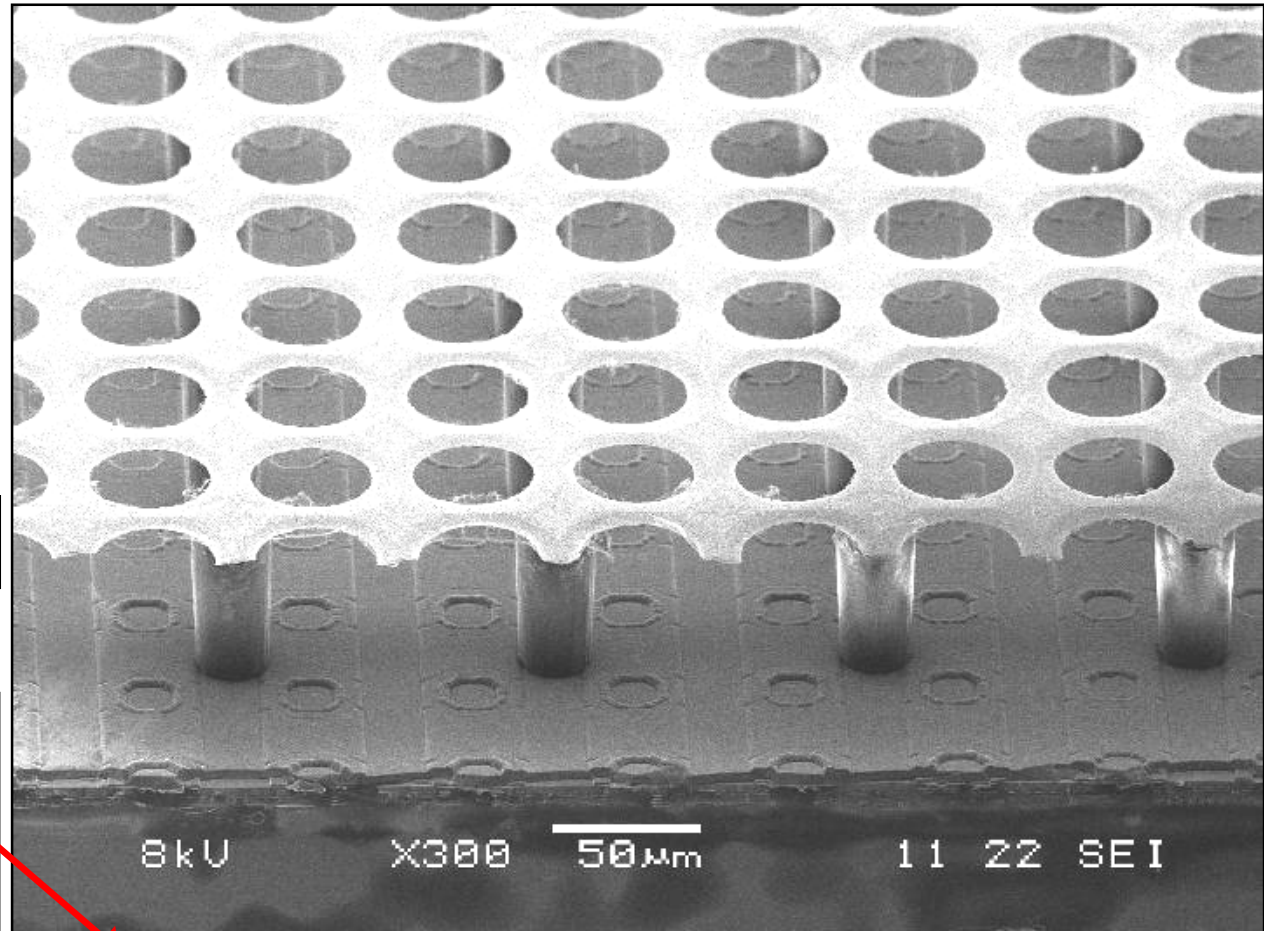
Timepix chip:

- 256x256 pixels
- pixel:  $55 \times 55 \mu\text{m}^2$
- active surface:  $14 \times 14 \text{ mm}^2$

MESA+: Ingrid

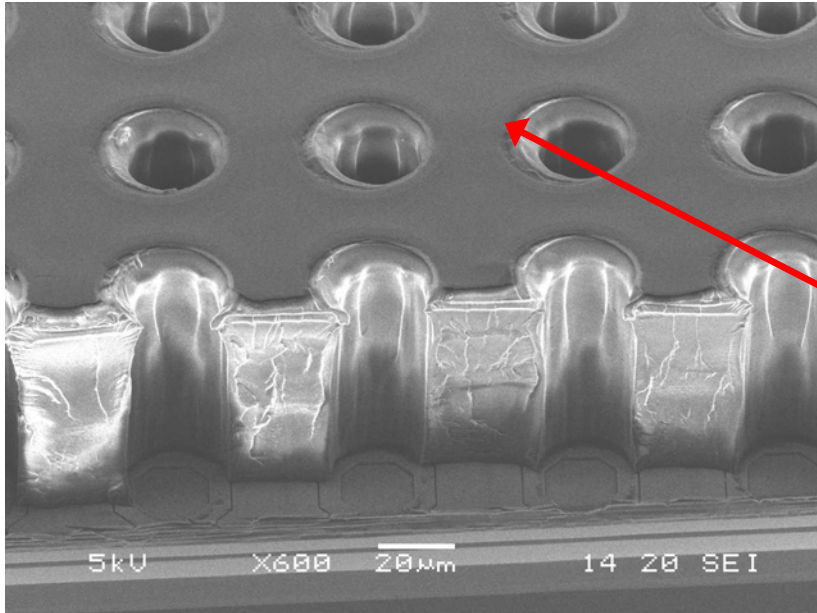
IMT Neuchatel:

15 or 20  $\mu\text{m}$  highly resistive aSi:H protection layer



Now also  $\text{Si}_3\text{N}_4$  protection layers ( $7 \mu\text{m}_2$ )

# Alternative Grid structures



## GemGrids

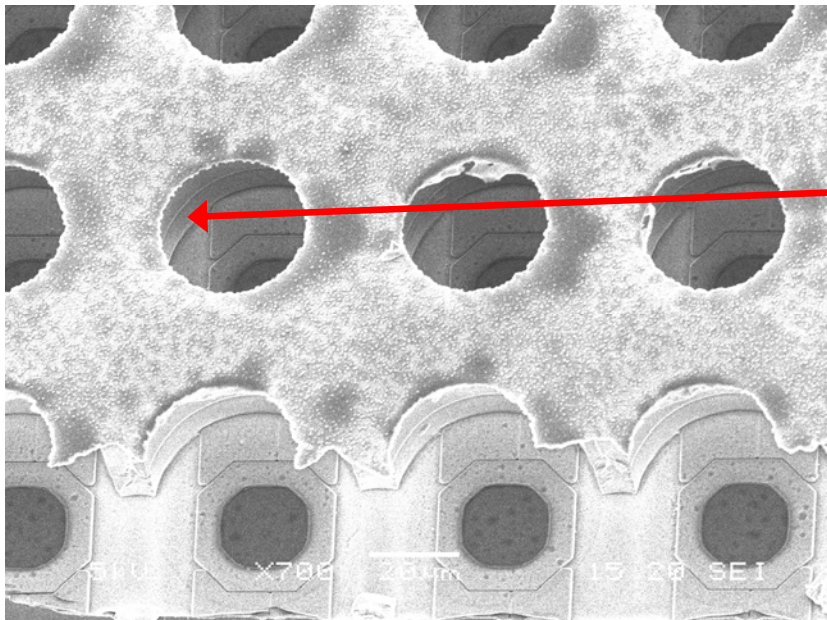
(mechanically more robust than Ingrids)

- recessed metal:

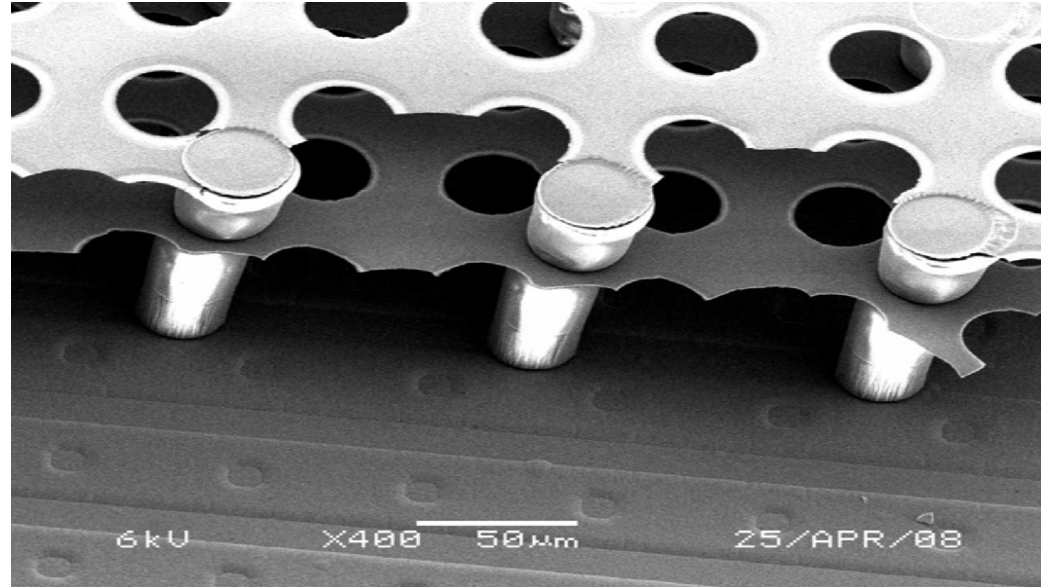
Much less gain than with pillars (micromegas-like)

- recessed insulator:

Somewhat less gain, but OK



## TwinGrid



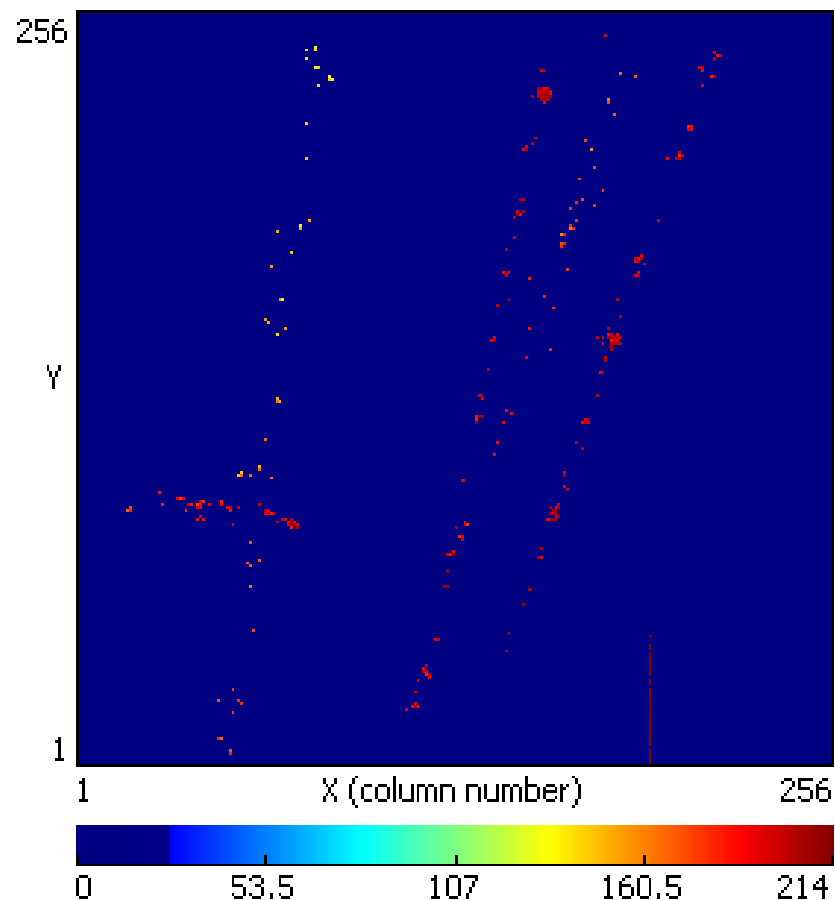
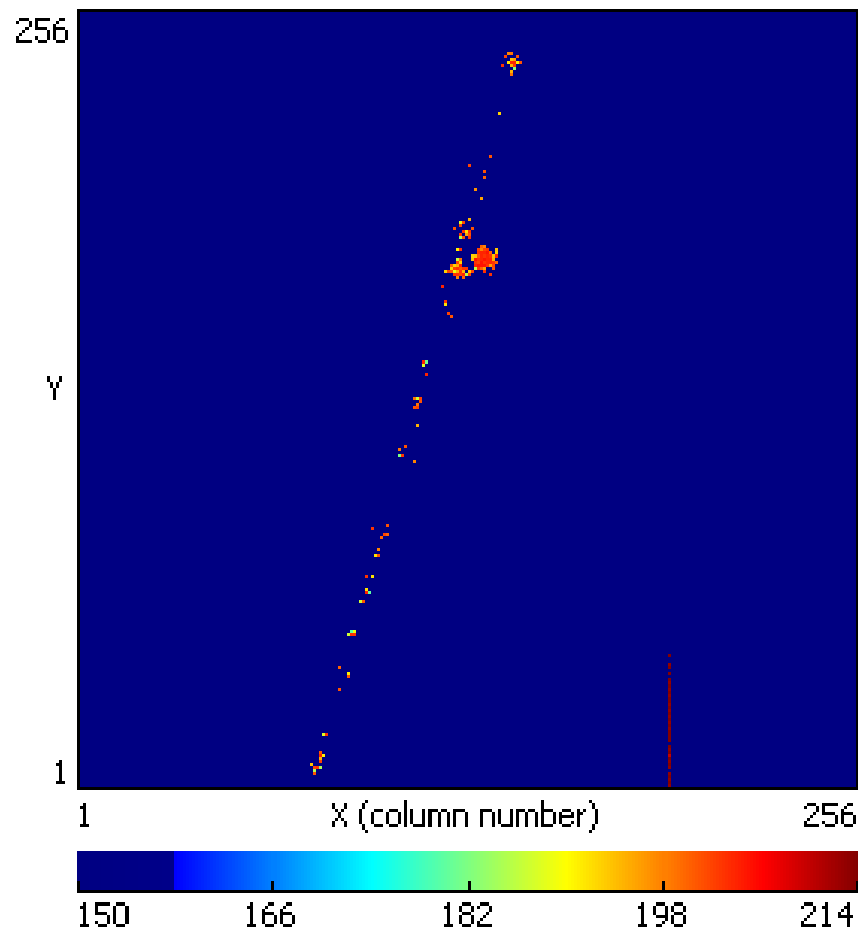
### Possible advantages:

- Separate high-gain region from anode
- Or share total gain over the two regions;  
→ Both give reduction of discharge probability
- Lower ion backflow: not yet measured

**It works!** (but not yet perfect)

# Some tracks

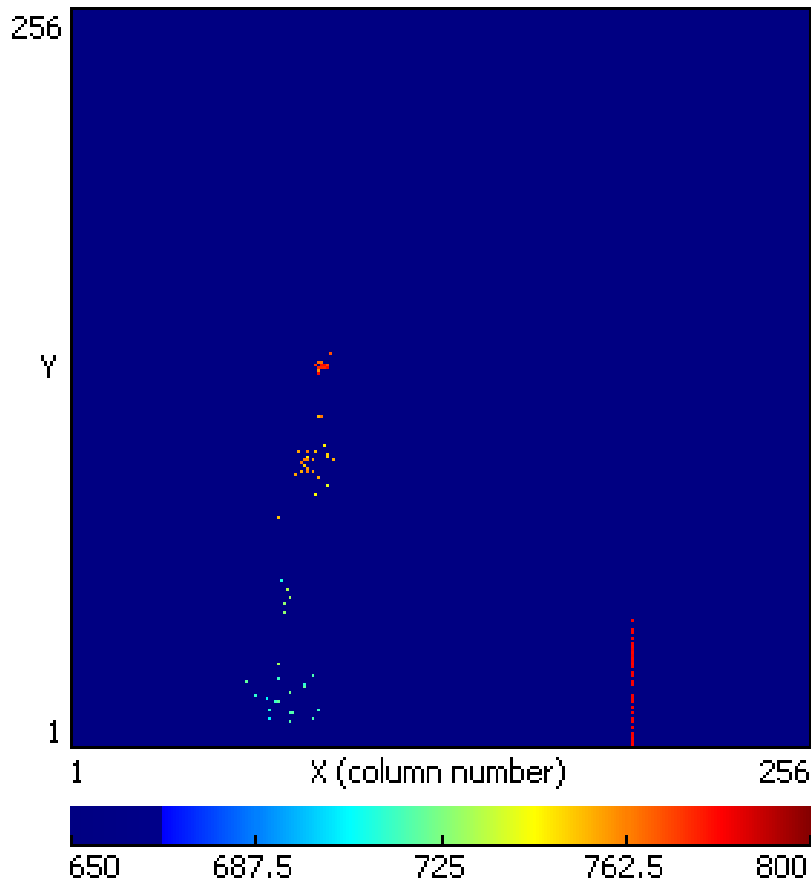
(with Ingrid in 5 GeV CERN T9 testbeam)



Colour code is drifttime

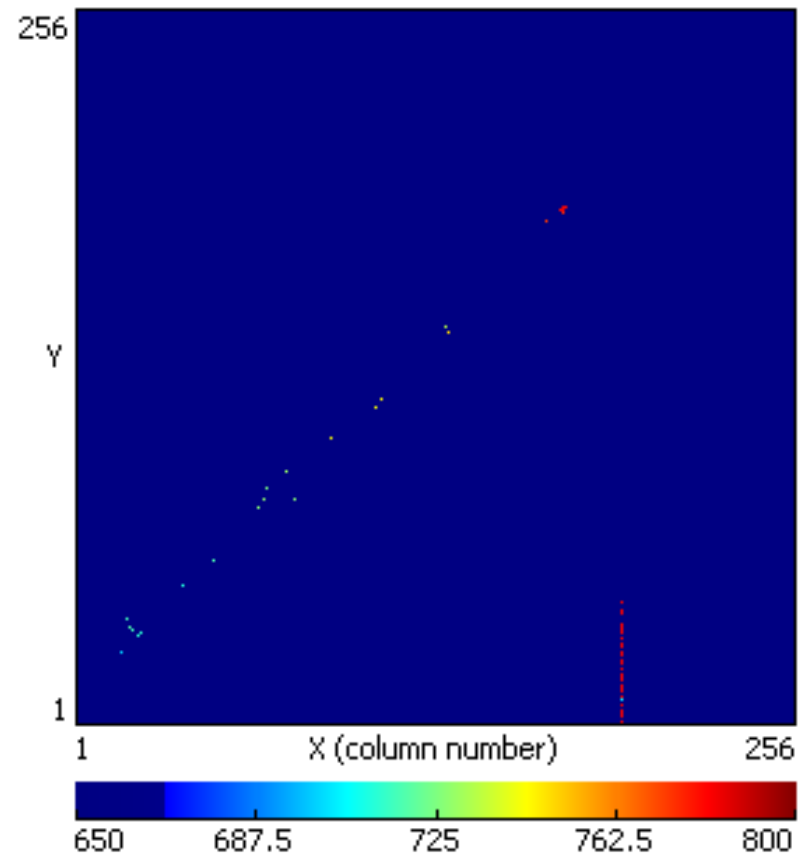
Cosmic tracks traversing  $\sim 30$  mm drift space  
Ingrid and Ar-**CF4**-iC4H10 (95/3/2%)

0 T



“large” diffusion

1 T

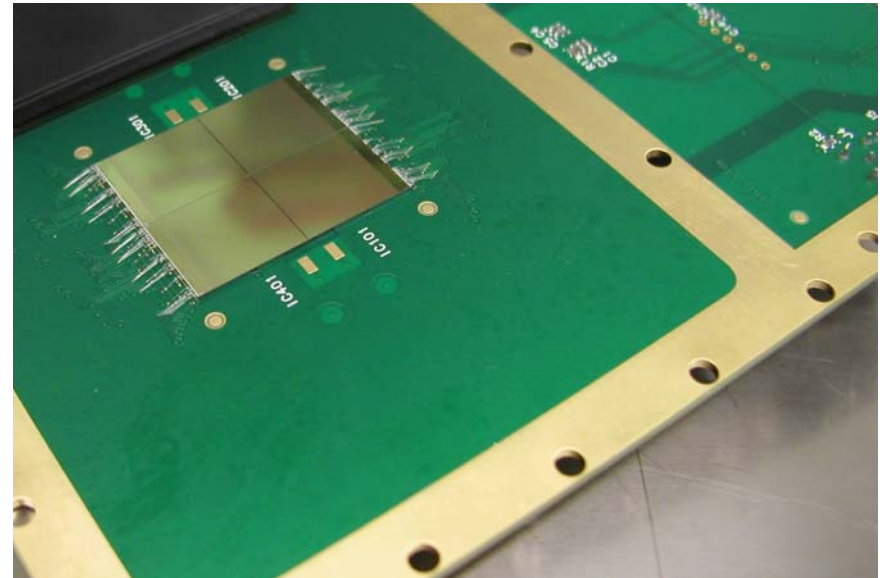


“little” diffusion



# Work in progress

- (Post) processing in Twente.
  - Both  $\text{Si}_3\text{N}_4$  and InGrid can be applied.
  - Treating chip squares of 3X3 timepix chips instead of individual chips.
  - Search for high res InGrids. ( $\text{Si}_3\text{N}_4$ )
- Optimize protection and signal integrity.
  - Discharge test structures.
- Recovering from problems with InGrids production; delivering soon
- Scaling up.
  - 4 chip detectors (3X3 cm): soon
  - 64 chip detector (12X12 cm): later in 2009/10
- Timepix2 development



# Cluster counting with Timepix

A few plots from Master thesis  
Lucie de Nooij



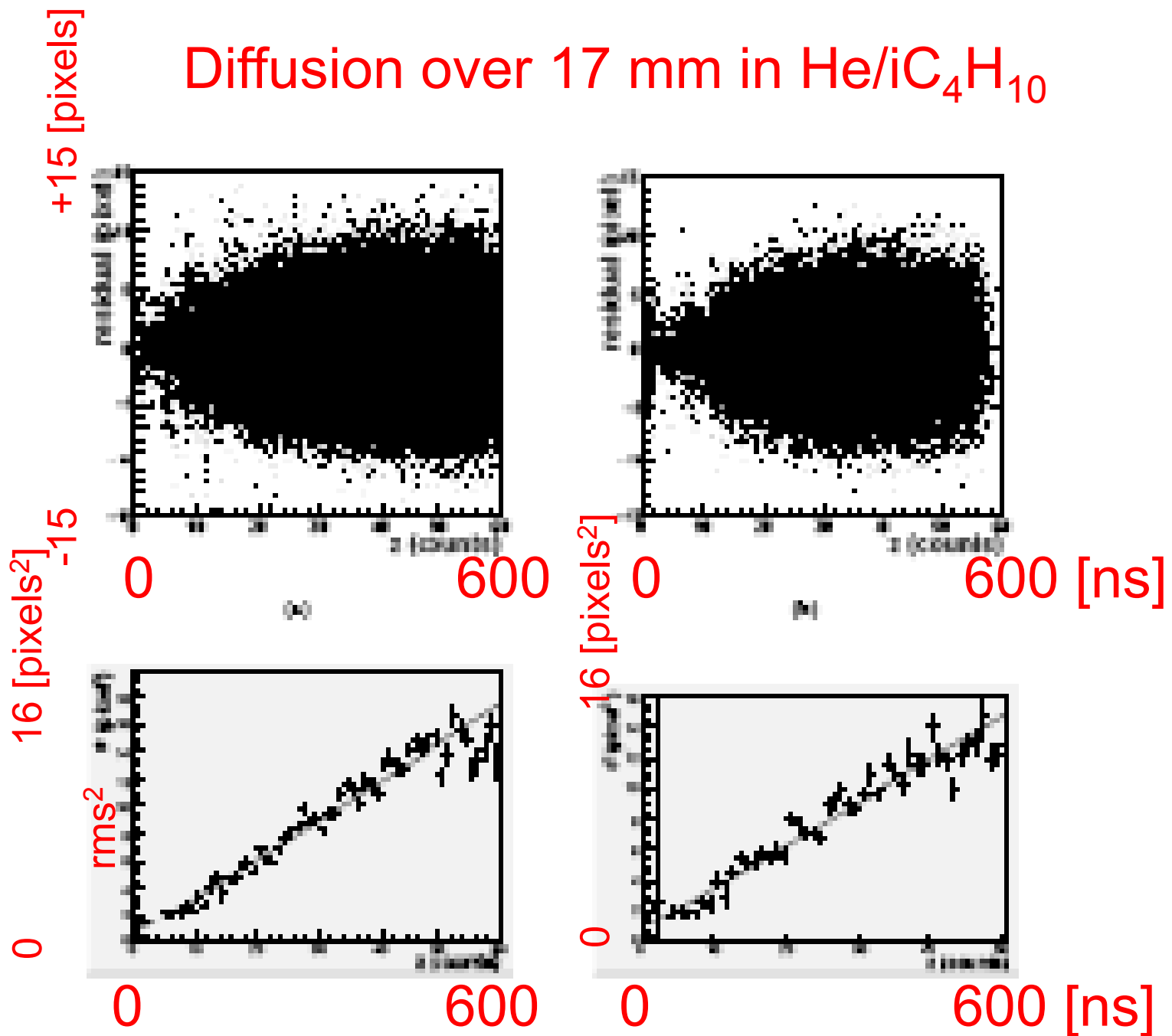
# Data from 5 GeV $\pi/e$ testbeam

- Gases used:
  - He/iC<sub>4</sub>H<sub>10</sub> 80/20
  - Xe/CO<sub>2</sub> 70/30
  - Ar/CF<sub>4</sub>/iC<sub>4</sub>H<sub>10</sub> 95/3/2
  - Ar/CO<sub>2</sub> 70/30

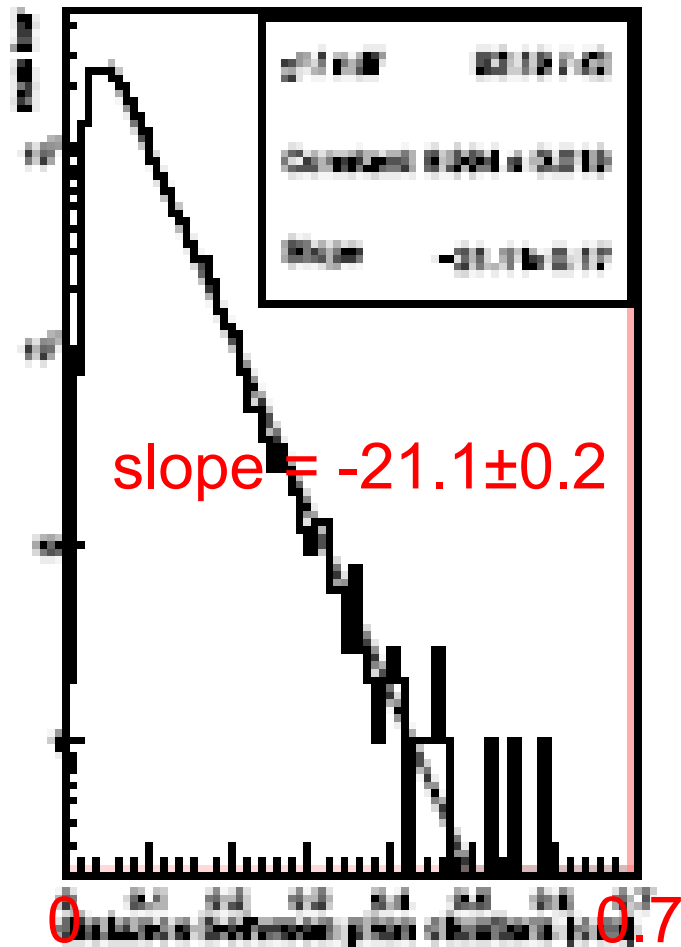
# Data analysis

- Track search/reconstruction using Hough transforms
- 2D and 3D track fits
- Drift velocity measurements (value for  $\text{Ar}/\text{CF}_4/\text{iC}_4\text{H}_{10}$  low by almost factor 2)
- Diffusion measurements:  $\text{He}/\text{iC}_4\text{H}_{10}$  “OK”  
other mixtures “off”
- Cluster distances and cluster counting

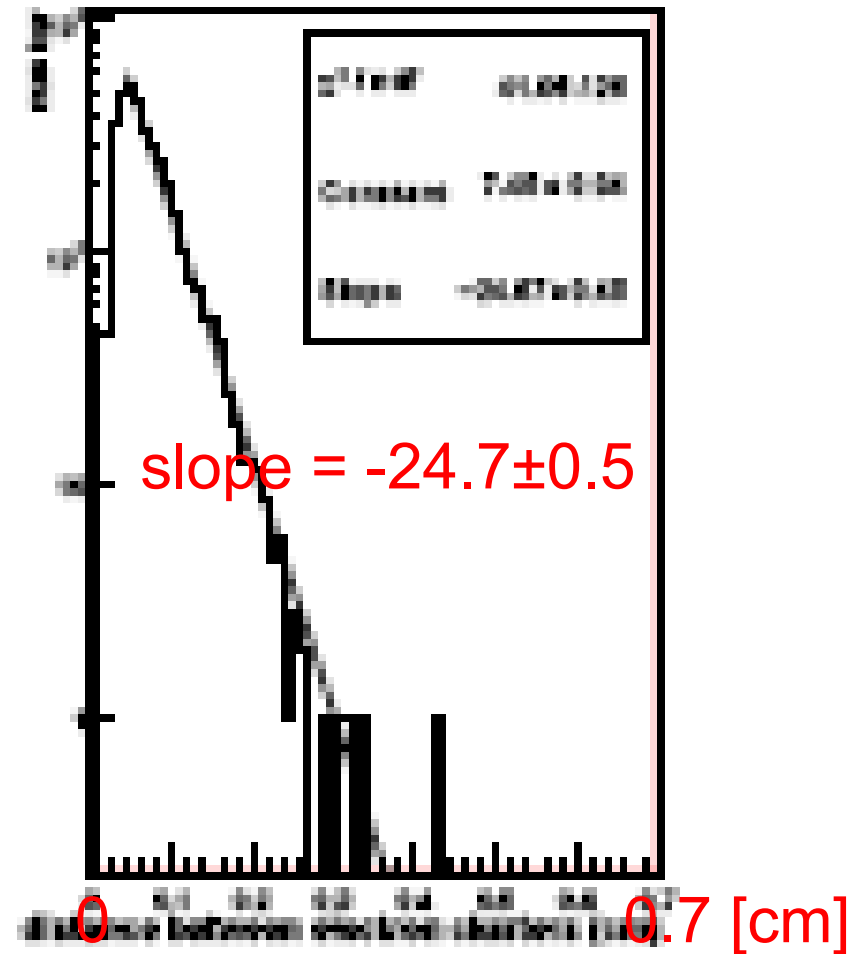
# Diffusion over 17 mm in He/iC<sub>4</sub>H<sub>10</sub>



# Cluster distance distribution in He/iC<sub>4</sub>H<sub>10</sub>

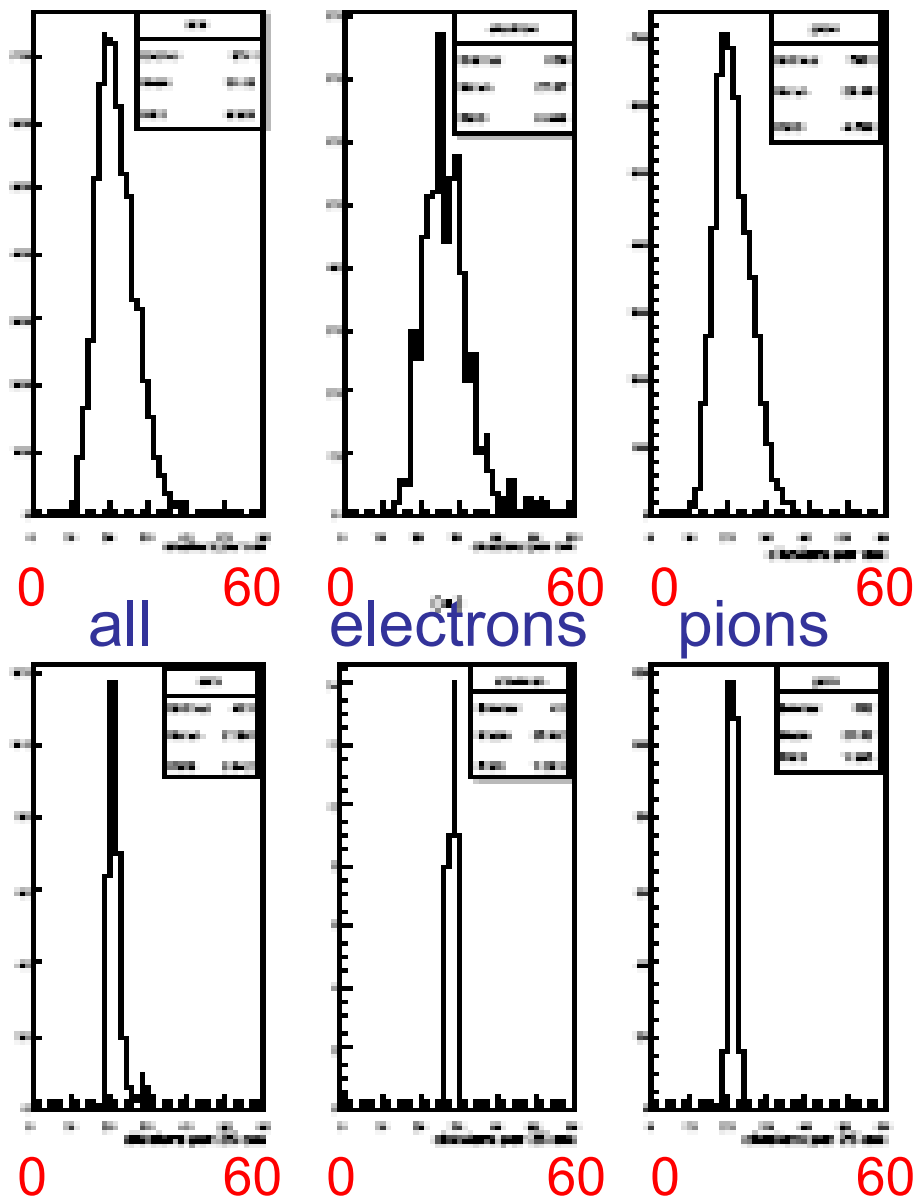


pions



electrons

# Cluster counting distribution in He/iC4H10



•Using 1 cm tracklength

Electrons:

Avg=27.1/cm rms=6.3

Pions: 21.0/cm 4.8

•Using 25 cm tracklength

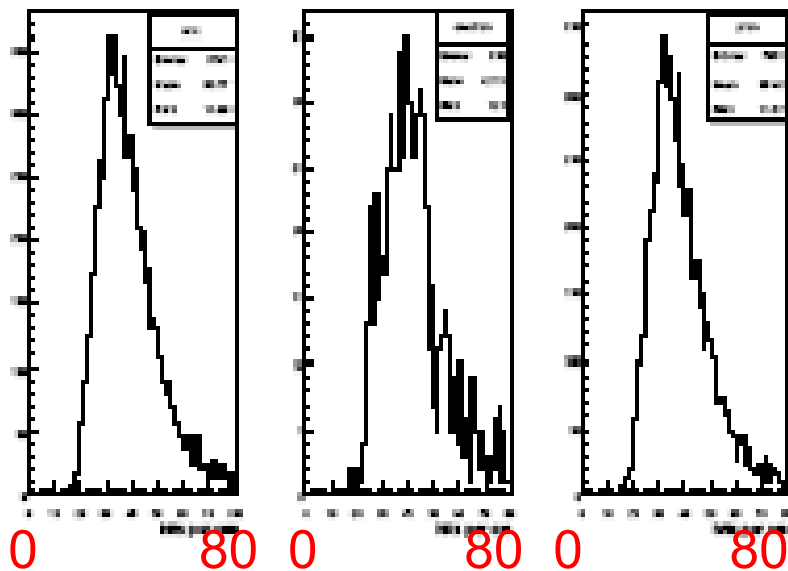
Electrons:

Avg=28.4/cm rms=1.2

Pions: 21.0/cm 1.2

4.4  $\sigma$  difference

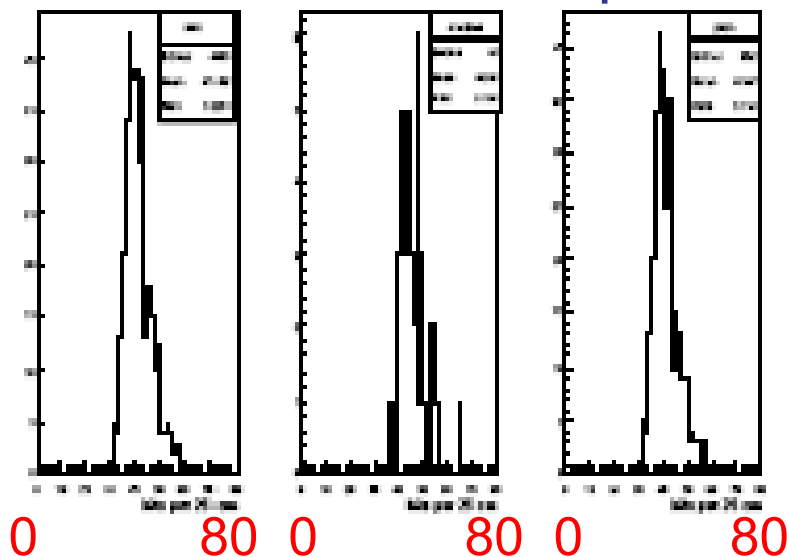
# Single hits counting distribution in He/iC4H10



all

electrons

pions



•Using 1 cm tracklength

Electrons:

Avg=42.2/cm rms=12.1

Pions: 38.4/cm 11.6

•Using 25 cm tracklength

Electrons:

Avg=46.0/cm rms=5.1

Pions: 41.5/cm 5.1

0.6  $\sigma$  difference

# Summary

- A lot of progress made in last ‘year’; not mentioned many details on energy and point resolution studies and on signal development (see PhD thesis Max Chefdeville, Jan.2009)
- First (prel.) results on cluster counting from 2008 beam tests (Master thesis Lucie de Nooij, Jan.2009)
- Part of the technology is ready:
  - Very good energy resolution for Ingrid devices
  - Ion backflow at the few per-mil level at high field ratio
- Discharge protection seems working for Ingrid (and Micromegas) devices under “normal” conditions

## Next:

- Build larger multi-chip detector systems with fast readout
- Through-Si connections & full 8” wafer post-processing



Backup for “amusement”

# A 5 cm<sup>3</sup> TPC (two electron tracks from <sup>90</sup>Sr source)

$B = 0.2 \text{ T}$

